

What is claim d is:

1. An emulsion composition in which a metallic oxide is included in an emulsion containing a silicone resin.
2. An emulsion composition of Claim 1, wherein the metallic oxide comprises kaolin.
3. An emulsion composition of Claim 1, wherein the metallic oxide comprises silicon oxide.
4. An emulsion composition of Claim 1, wherein the metallic oxide comprises aluminum oxide.
5. An emulsion composition of Claim 1, wherein the metallic oxide comprises at least one of titanium oxide, zirconium oxide; antimony oxide, germanium oxide; boron oxide; calcium oxide; barium oxide; strontium oxide; bismuth oxide; copper oxide; and talc.
6. An emulsion composition of Claim 1, including at least one nitride from the group including silicon nitride, aluminum nitride, zirconium nitride, copper nitride, strontium nitride, titanium nitride, and barium nitride.
7. An emulsion composition of Claim 1, wherein the proportion of the emulsion containing the silicone resin in the emulsion composition is 30-70 weight percent.
8. An emulsion composition of Claim 2, wherein the proportion of kaolin in the emulsion composition is 7-20 weight percent.
9. A coating film which is formed from an emulsion composition in which a metallic oxide is included in an emulsion containing a silicone resin.
10. A coating film of Claim 9, wherein the metallic oxide comprises kaolin.
11. A cooling mechanism in which a coating film formed from an emulsion composition in which a metallic oxide is included in an

emulsion containing a silicone resin, is formed on at least one portion of surface of a substrate.

12. A cooling mechanism of Claim 11, wherein the metallic oxide comprises kaolin.

13. A cooling mechanism of Claim 11, wherein the coating film is a non-conductive radiating coating film.

14. A cooling mechanism of Claim 11, wherein the substrate is the main body of an electronic part.

15. A cooling mechanism of Claim 11, wherein the substrate is a lead terminal of an electronic part.

16. A cooling mechanism of Claim 11, wherein the substrate is a printed circuit board.

17. A cooling mechanism of Claim 11, wherein the substrate is a printed circuit board on which an electronic part has been installed.

18. A cooling mechanism of Claim 17, wherein the coating film is formed on the printed circuit board on which an electronic part has been installed via a resist layer.